

FIG. 1

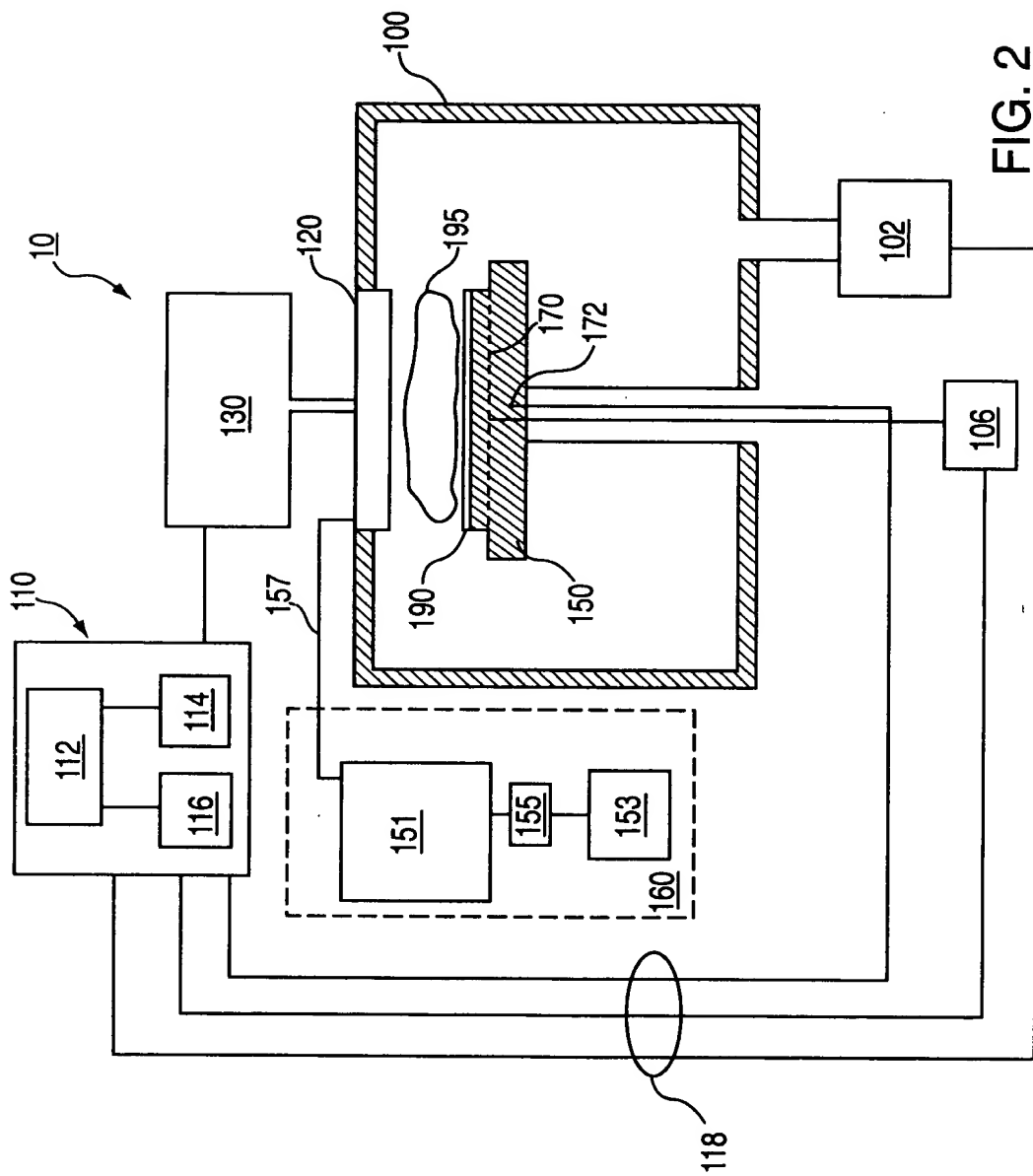


FIG. 2

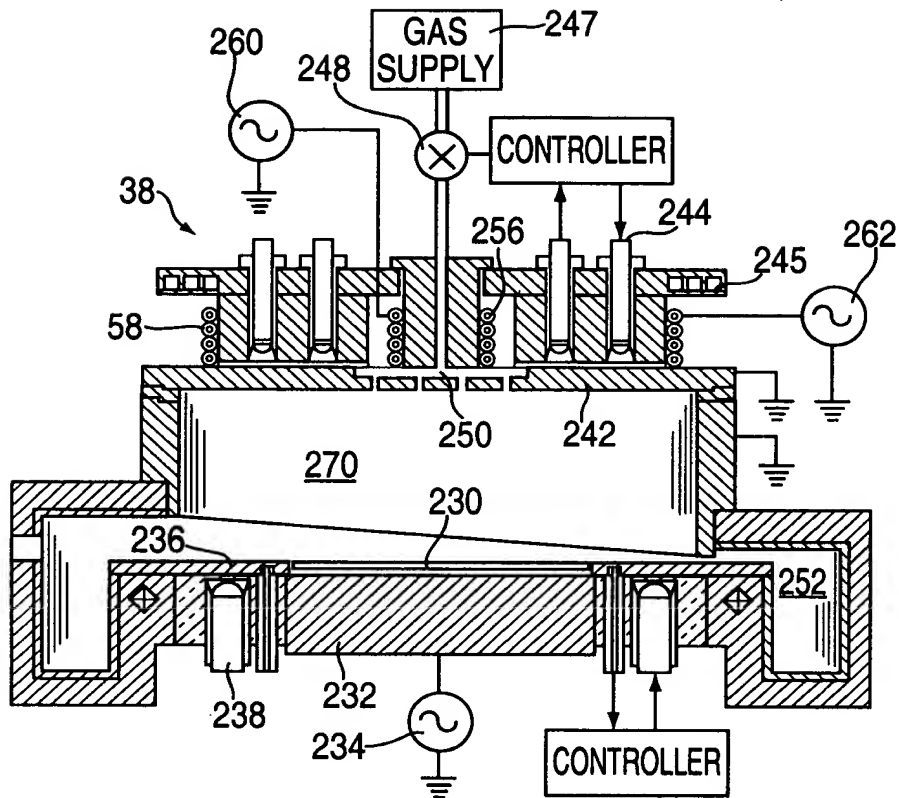


FIG. 3

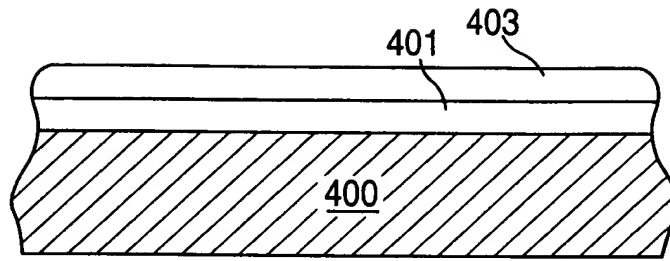


FIG. 4a

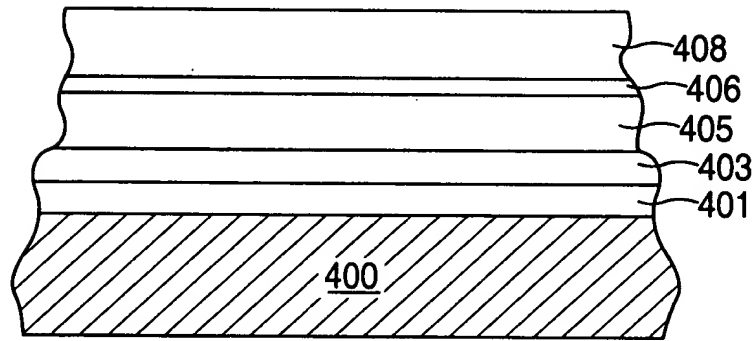


FIG. 4b

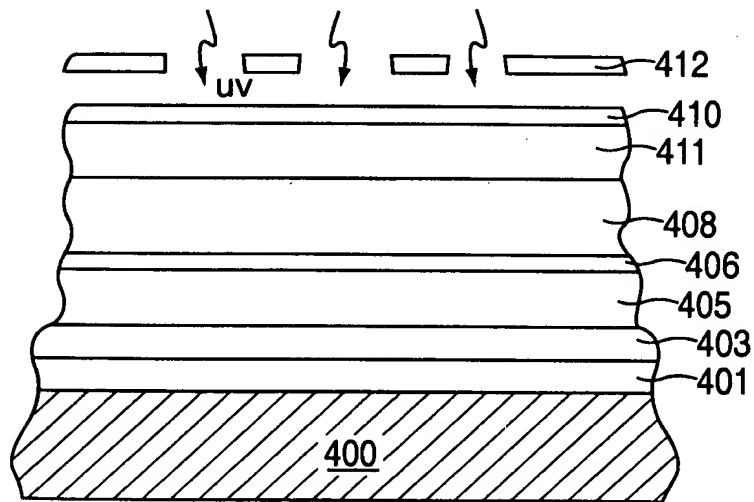


FIG. 4c

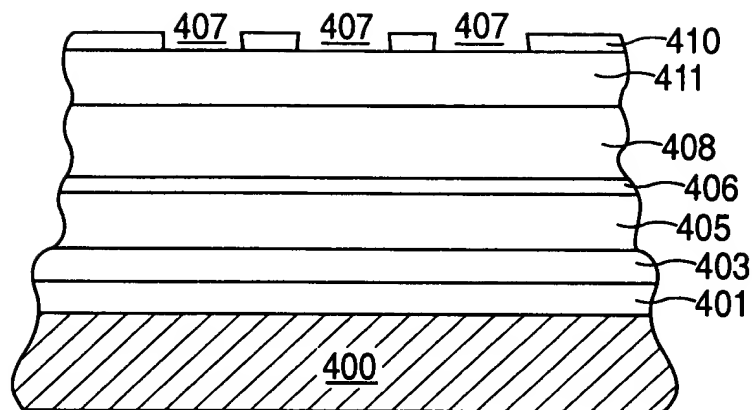


FIG. 4d

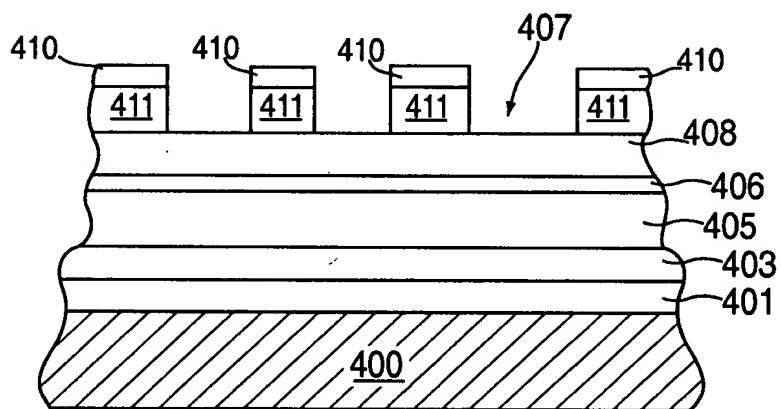


FIG. 4e

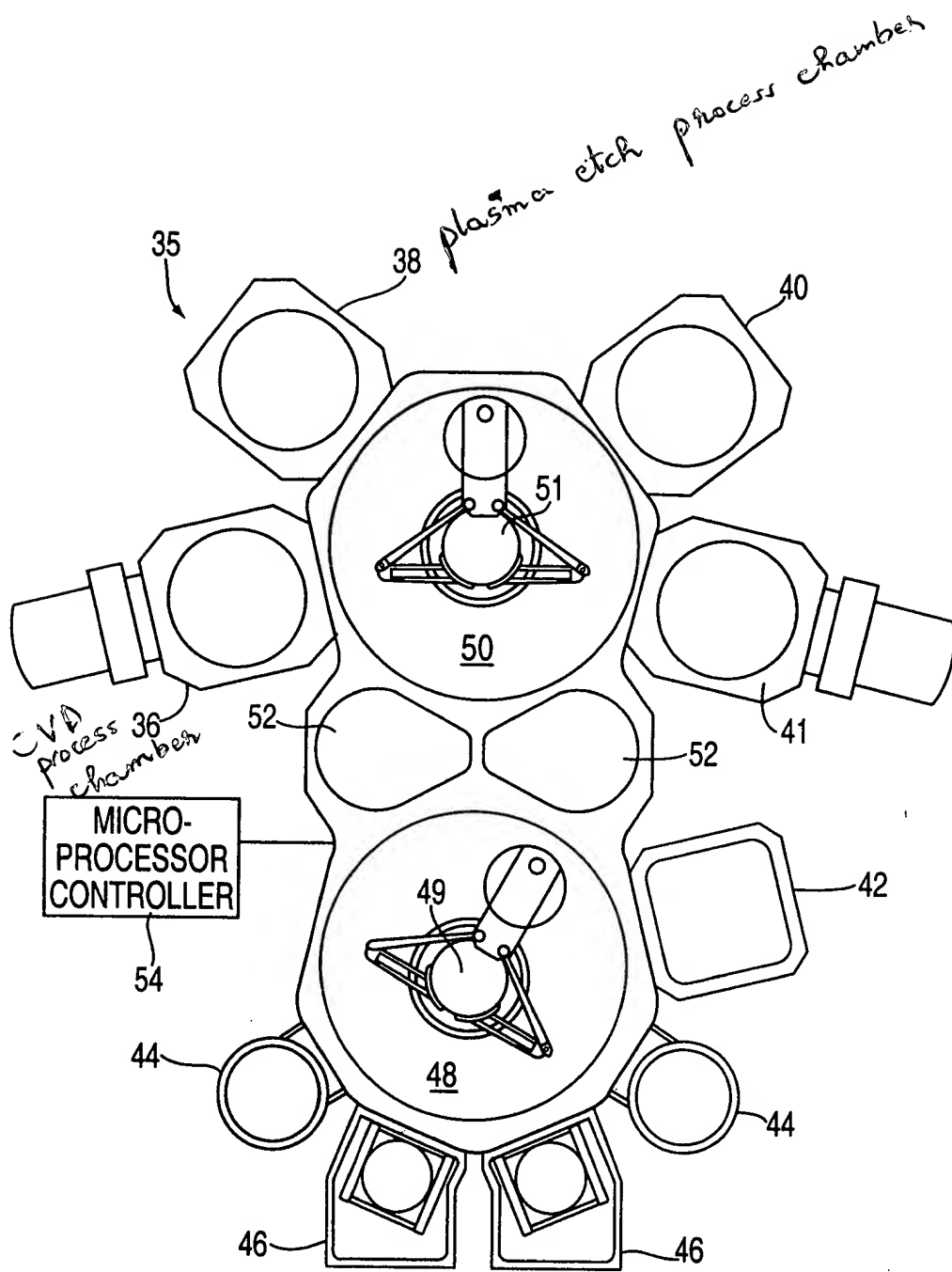


FIG. 1

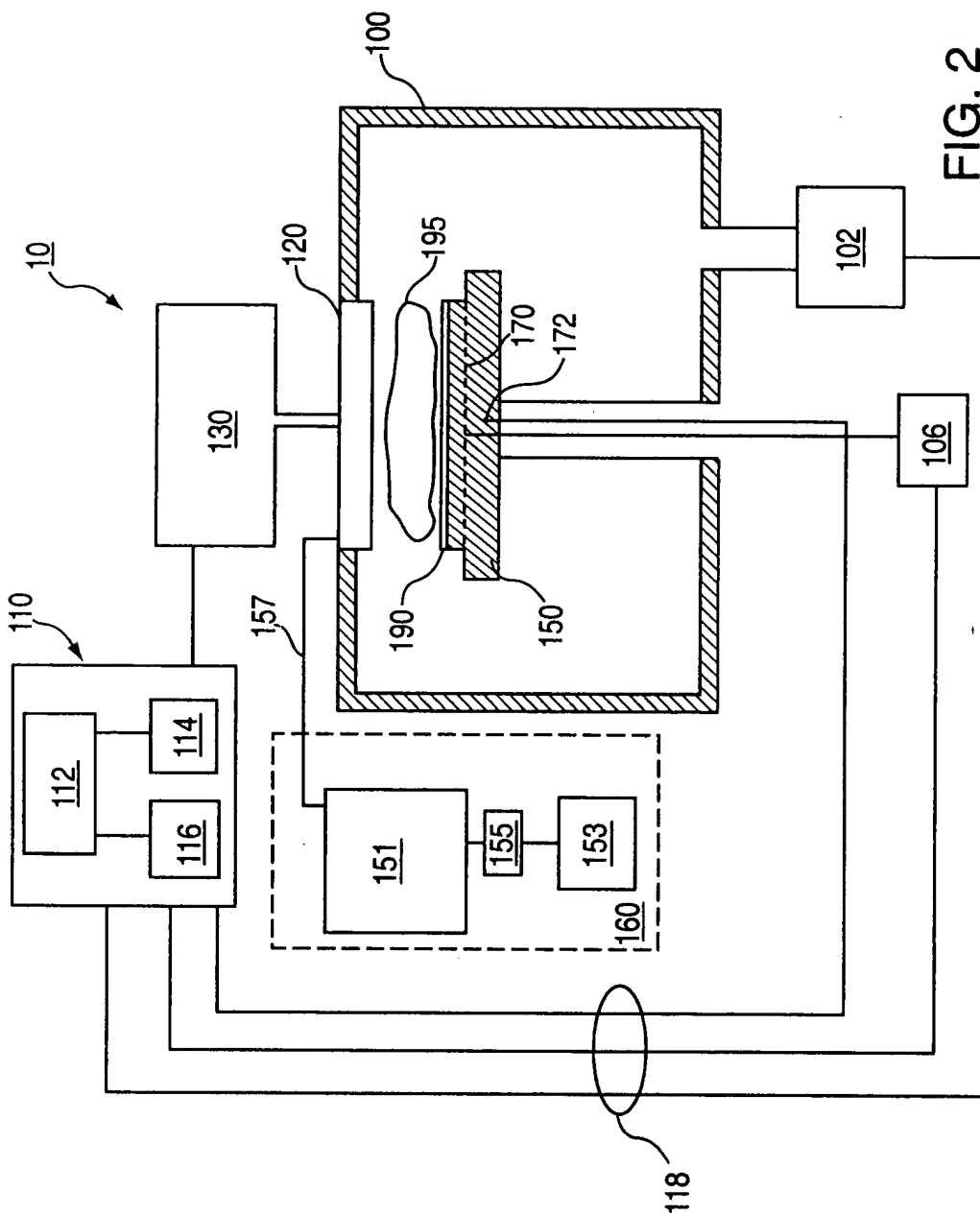


FIG. 2

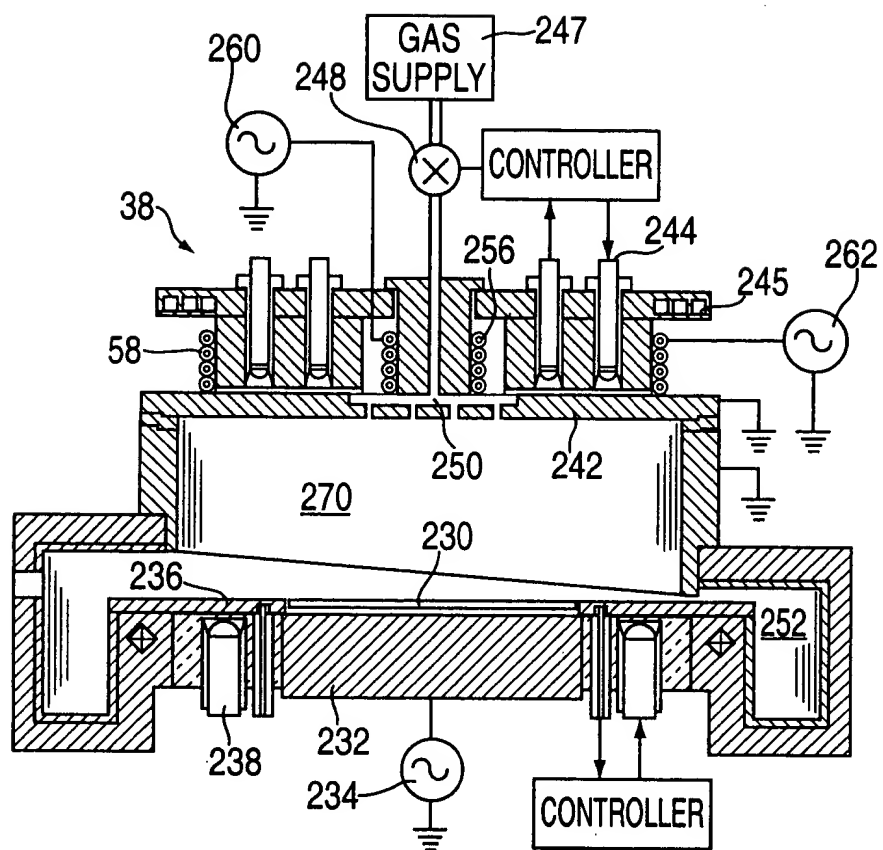


FIG. 3



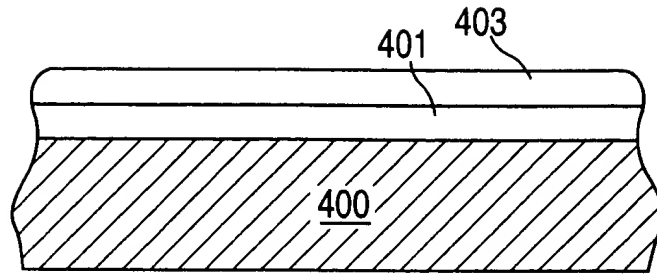


FIG. 4a

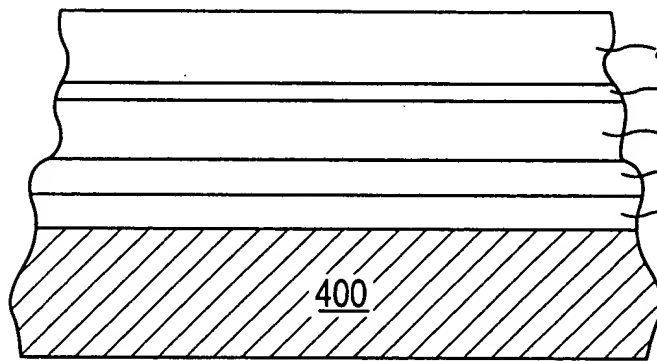


FIG. 4b

408 → 2nd organo silicate layer  
 406 → silicon oxide layer  
 405 → 1st organo silicate layer  
 403 → barrier layer (silicon carbide)  
 401 → copper leads  
 Silicon substrate

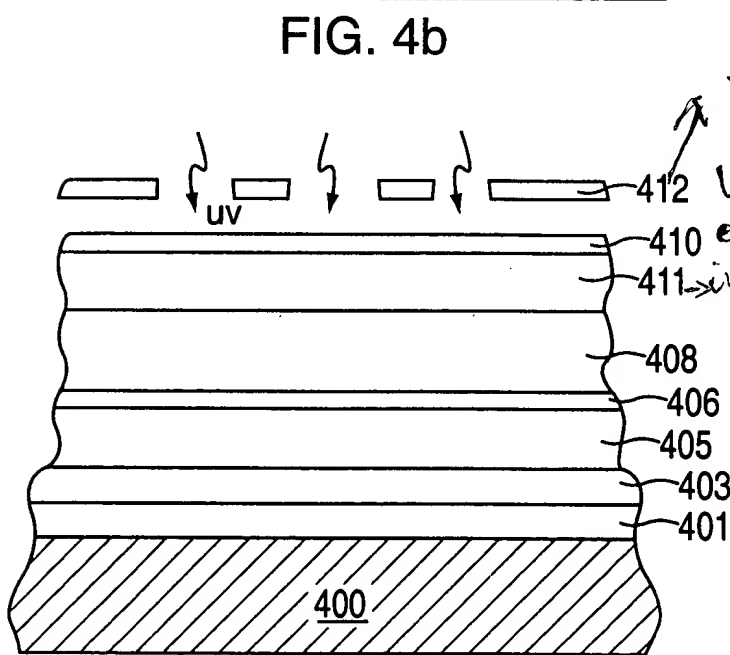


FIG. 4c

interconnect lines  
 412 UV radiation via mask  
 410 energy sensitive resist  
 411 intermediate layer (mask)

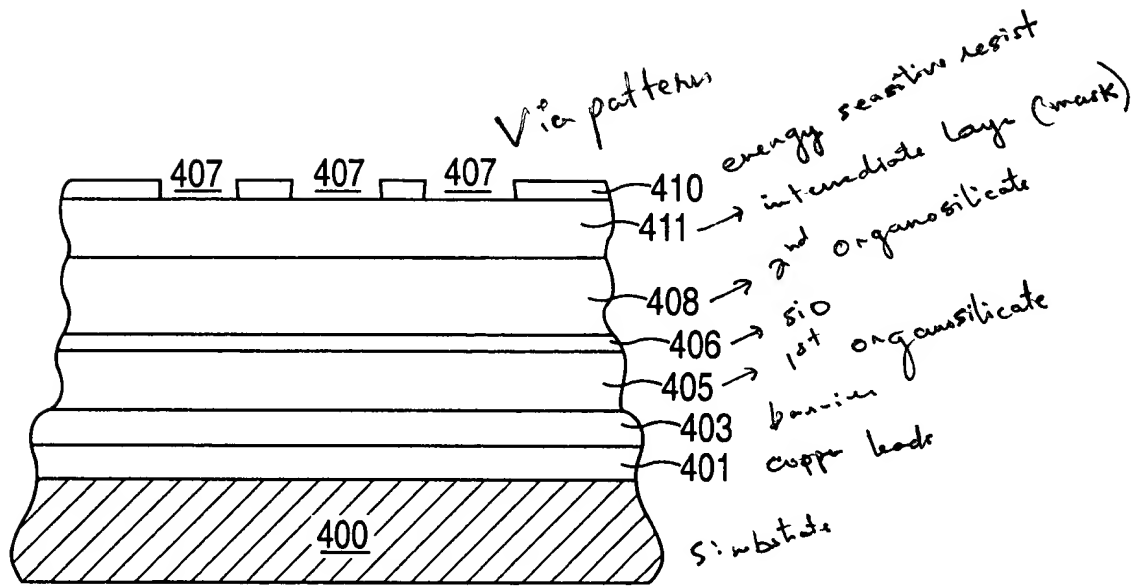


FIG. 4d

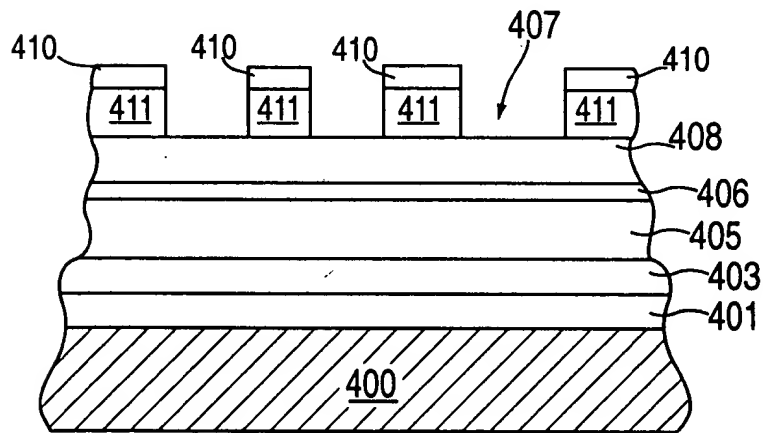


FIG. 4e